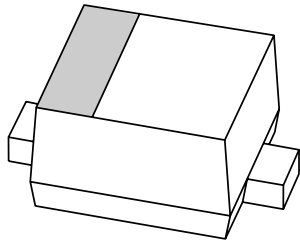


# DATA SHEET



## **1PS79SB10** Schottky barrier diode

Product data sheet

1998 Jul 16

# Schottky barrier diode

# 1PS79SB10

## FEATURES

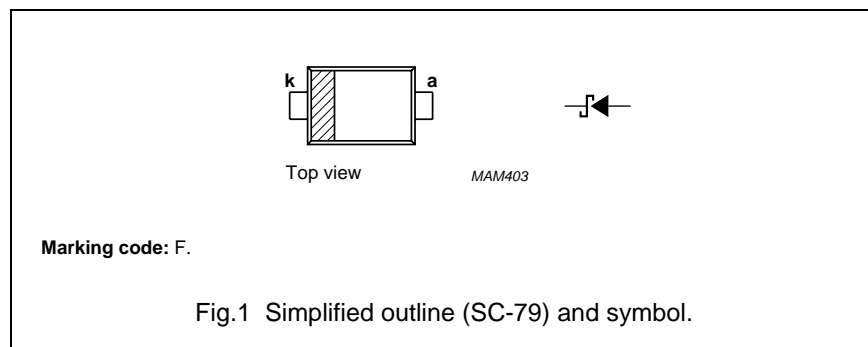
- Low forward voltage
- Guard ring protected
- Ultra small plastic SMD package.

## APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes.

## DESCRIPTION

Planar Schottky barrier diode encapsulated in a SC-79 ultra small plastic SMD package.



## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage		–	30	V
$I_F$	continuous forward current		–	200	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1 \text{ s}; \delta \leq 0.5$	–	300	mA
$I_{FSM}$	non-repetitive peak forward current	$t_p < 10 \text{ ms}$	–	600	mA
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	125	°C
$T_{amb}$	operating ambient temperature		–65	+125	°C

## Schottky barrier diode

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**ELECTRICAL CHARACTERISTICS**T<sub>amb</sub> = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	continuous forward voltage	see Fig.2 I <sub>F</sub> = 0.1 mA I <sub>F</sub> = 1 mA I <sub>F</sub> = 10 mA I <sub>F</sub> = 30 mA I <sub>F</sub> = 100 mA	240 320 400 500 800	mV mV mV mV mV
I <sub>R</sub>	continuous reverse current	V <sub>R</sub> = 25 V; note 1; see Fig.3	2	μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; see Fig.4	10	pF

**Note**

1. Pulsed test: t<sub>p</sub> = 300 μs; δ = 0.02.

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	450	K/W

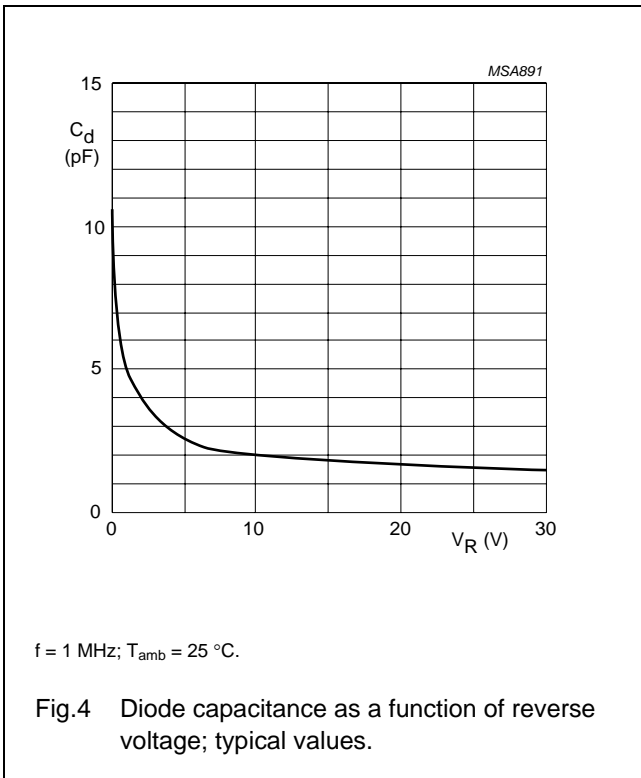
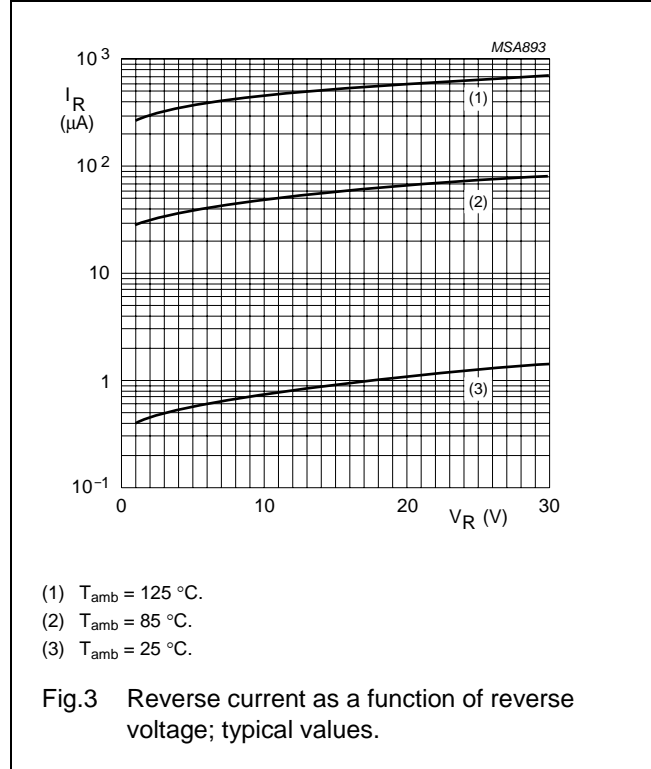
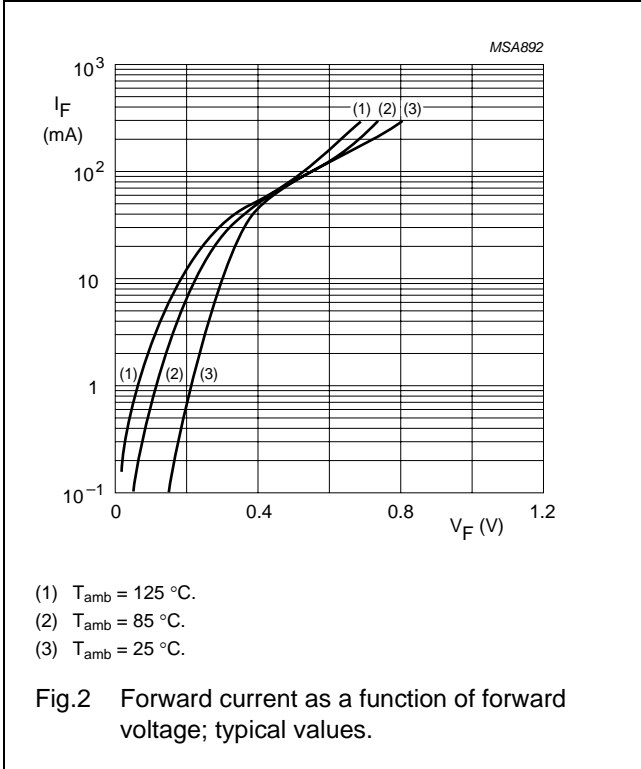
**Note**

1. Refer to SC-79 standard mounting conditions.

Schottky barrier diode

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GRAPHICAL DATA



# Schottky barrier diode

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## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD523

**DIMENSIONS (mm are the original dimensions)**

UNIT	A	bp	c	D	E	HE	v
mm	0.65 0.58	0.34 0.26	0.17 0.11	1.25 1.15	0.85 0.75	1.65 1.55	0.1

**Note**  
1. The marking bar indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD523			SC-79			<del>98-11-25</del> 02-12-13

## Schottky barrier diode

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## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

## Notes

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## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

For additional information please visit: <http://www.nxp.com>

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